# MC74HCT20A

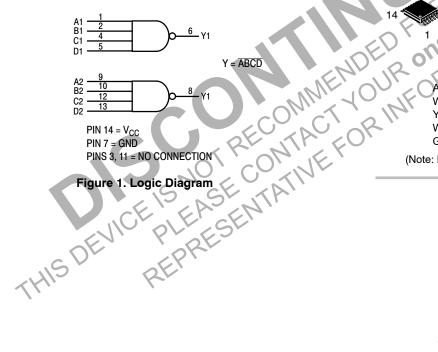
# **Dual 4-Input NAND Gate** with LSTTL-Compatible **Inputs**

# **High-Performance Silicon-Gate CMOS**

The MC74HCT20A is identical in pinout to the LS20. The device inputs are compatible with standard CMOS LSTTL outputs.

#### **Features**

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 4.5 V to 5.5 V
- Low Input Current: 1 μA
- High Noise Immunity Characteristic of CMOS Devices
- These are Pb-Free Devices





#### ON Semiconductor®

http://onsemi.com

#### **MARKING DIAGRAMS**



SOIC-14 **D SUFFIX** CASE 751A







= Assembly Location

= Wafer Lot = Year WW, W = Work Week G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

#### **PIN ASSIGNMENT**

			_
A1 [	1●		v <sub>cc</sub>
B1 [	2	13	D2
NC [		12	C2
C1 [	4	11	NC
D1 [		10	] B2
Y1 [	6	9	A2
GND [	7	8	Y2

#### **FUNCTION TABLE**

	Inputs				
Α	В	С	D	Υ	
L	Х	Х	Х	Н	
X	L	Х	Х	Н	
X	X	L	X	Н	
X	X	Х	L	Н	
Н	Н	Н	Н	L	

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

#### MC74HCT20A

#### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V <sub>in</sub>	DC Input Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> +0.5	V
V <sub>out</sub>	DC Output Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> +0.5	V
I <sub>in</sub>	DC Input Current, per Pin	±20	mA
I <sub>out</sub>	DC Output Current, per Pin	±25	mA
I <sub>CC</sub>	DC Supply Current, V <sub>CC</sub> and GND Pins	±50	mA
P <sub>D</sub>	Power Dissipation in Still Air SOIC Package TSSOP Package	500 450	mW
T <sub>stg</sub>	Storage Temperature	-65 to +150	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, Vin and Vout should be constrained to the range GND  $\leq$  ( $V_{in}$  or  $V_{out}$ )  $\leq$   $V_{CC}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V<sub>CC</sub>). Unused outputs must be left open.

#### RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	4.5	5.5	V
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage (Referenced to GND)	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature Range, All Package Types	- 55	+ 125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise/Fall Time (Figure 1)	0	500	ns

#### DC CHARACTERISTICS (Voltages Referenced to GND)

T <sub>stg</sub>	Storage Temperature		-65 to	+150	°C	Unuse	d outputs	must be let	t open.
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.    RECOMMENDED OPERATING CONDITIONS   Symbol   Parameter   Min   Max   Unit   V <sub>CC</sub>   DC Supply Voltage (Referenced to GND)   4.5   5.5   V   V <sub>in</sub> , V <sub>out</sub>   DC Input Voltage, Output Voltage (Referenced to GND)   0   V <sub>CC</sub>   V									
Symbol	Parameter		Min	Max	Unit	10	DV		
V <sub>CC</sub>	DC Supply Voltage (Referenced to GN	ID)	4.5	5.5	V	IEV	~		
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage (Refer	enced to GND)	0	V <sub>CC</sub>	V	2			
T <sub>A</sub>	Operating Temperature Range, All Page	ckage Types	- 55	+ 125	°C.	), <sup>2</sup> W <sub>1</sub>	M		
t <sub>r</sub> , t <sub>f</sub>	Input Rise/Fall Time (Figure 1)		0	500	ns	156, 11	O.		
DC CHA	V <sub>in</sub> , V <sub>out</sub> DC Input Voltage, Output Voltage (Referenced to GND) 0 V <sub>CC</sub> V  T <sub>A</sub> Operating Temperature Range, All Package Types 55 + 125 °C  t <sub>r</sub> , t <sub>f</sub> Input Rise/Fall Time (Figure 1) 0 500 ns  DC CHARACTERISTICS (Voltages Referenced to GND)								
			$N_{III}$	40,	V <sub>CC</sub>		nteed Lin	1	
Symbol	Parameter		ndition	· R	\ \ V	-55 to 25°C	≤85°C	≤125°C	Unit
$V_{IH}$	Minimum High-Level Input Voltage	$V_{out} = 0.1V$ $ I_{out}  \le 20\mu A$		70	4.5 5.5	2.0 2.0	2.0 2.0	2.0 2.0	V
V <sub>IL</sub>	Maximum Low-Level Input Voltage	$V_{out} = V_{CC} - Q$ $ I_{out}  \le 20\mu A$	):1V		4.5 5.5	0.8 0.8	0.8 0.8	0.8 0.8	V
V <sub>OH</sub>	Minimum High-Level Output Voltage	$V_{in} = V_{iL}$ $ I_{out}  \le 20\mu A$			4.5 5.5	4.4 5.4	4.4 5.4	4.4 5.4	V
	OF PAR	$V_{in} = V_{IL}$	I <sub>out</sub>	$\leq$ 4.0mA	4.5	3.98	3.84	3.70	
V <sub>OL</sub>	Maximum Low-Level Output Voltage	$V_{in} = V_{IH}$ $ I_{out}  \le 20\mu A$			4.5 5.5	0.1 0.1	0.1 0.1	0.1 0.1	V
		$V_{in} = V_{IH}$	I <sub>out</sub>	≤ 4.0mA	4.5	0.26	0.33	0.40	
l <sub>in</sub>	Maximum Input Leakage Current	$V_{in} = V_{CC}$ or $C$	GND		5.5	±0.1	±1.0	±1.0	μΑ
Icc	Maximum Quiescent Supply Current (per Package)	$V_{in} = V_{CC}$ or $O$ $I_{out} = O\mu A$	AND		5.5	1	10	40	μА
$\Delta I_{CC}$	Additional Quiescent Supply Current	V <sub>in</sub> = 2.4V, An V <sub>in</sub> = V <sub>CC</sub> or 0	y One Inpu	ıt Inputs		≥ <b>–55</b> °C	25 to	125°C	
		$I_{out} = 0 \mu A$		pato	5.5	2.9	2	.4	mA

<sup>1.</sup> Information on typical parametric values can be found in Chapter 2 of the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

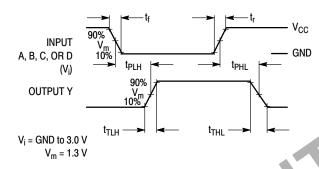
<sup>2.</sup> Total Supply Current =  $I_{CC} + \Sigma \Delta I_{CC}$ .

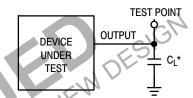
#### MC74HCT20A

#### AC ELECTRICAL CHARACTERISTICS ( $C_L$ = 50 pF, Input $t_r$ = $t_f$ = 6 ns, $V_{CC}$ = 5.0 V)

		Guaranteed Limit			
Symbol	Parameter	– 55 to 25°C	≤ <b>85</b> °C	≤ 125°C	Unit
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Input A, B, or C to Output Y (Figures 2 and 3)	28	35	42	ns
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output Transition Time, Any Output (Figures 2 and 3)	15	19	22	ns
C <sub>in</sub>	Maximum Input Capacitance	10	10	10	pF

Ī			Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
	$C_{PD}$	Power Dissipation Capacitance (Per Gate)	26	pF





\*Includes all probe and jig capacitance

Figure 3. Test Circuit

Figure 2. Switching Waveforms

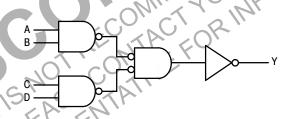


Figure 4. Expanded Logic Diagram (1/2 of the Device)

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MC74HCT20ADG	SOIC-14 (Pb-Free)	55 Units/Rail
MC74HCT20ADR2G	SOIC-14 (Pb-Free)	2500/Tape & Reel
MC74HCT20ADTR2G	TSSOP-14*	]

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>This package is inherently Pb-Free.

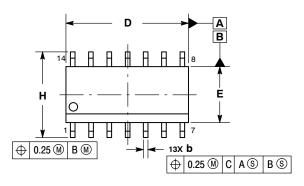


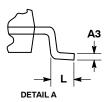


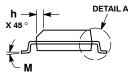
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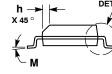
SOIC-14 NB CASE 751A-03 ISSUE L

**DATE 03 FEB 2016** 









- NOTES:
  1. DIMENSIONING AND TOLERANCING PER
  - ASME Y14.5M, 1994.
    CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT
- MAXIMUM MATERIAL CONDITION.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
- 5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE

	MILLIM	IETERS	INC	HES
DIM	MIN MAX		MIN	MAX
Α	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
АЗ	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
Е	3.80	4.00	0.150	0.157
е	1.27	BSC	0.050	BSC
Н	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0 °	7°	0 °	7°

#### **GENERIC MARKING DIAGRAM\***

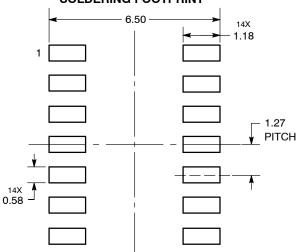


XXXXX = Specific Device Code Α = Assembly Location

WL = Wafer Lot Υ = Year WW = Work Week = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

### **SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

C SEATING PLANE

#### **STYLES ON PAGE 2**

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<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### SOIC-14 CASE 751A-03 ISSUE L

#### DATE 03 FEB 2016

STYLE 1: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. NO CONNECTION 5. ANODE/CATHODE 6. NO CONNECTION 7. ANODE/CATHODE 8. ANODE/CATHODE 9. ANODE/CATHODE 10. NO CONNECTION 11. ANODE/CATHODE 12. ANODE/CATHODE 13. NO CONNECTION 14. COMMON ANODE	STYLE 2: CANCELLED	STYLE 3: PIN 1. NO CONNECTION 2. ANODE 3. ANODE 4. NO CONNECTION 5. ANODE 6. NO CONNECTION 7. ANODE 8. ANODE 9. ANODE 10. NO CONNECTION 11. ANODE 12. ANODE 13. NO CONNECTION 14. COMMON CATHODE	STYLE 4: PIN 1. NO CONNECTION 2. CATHODE 3. CATHODE 4. NO CONNECTION 5. CATHODE 6. NO CONNECTION 7. CATHODE 8. CATHODE 9. CATHODE 10. NO CONNECTION 11. CATHODE 12. CATHODE 13. NO CONNECTION 14. COMMON ANODE
STYLE 5: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. ANODE/CATHODE 5. ANODE/CATHODE 6. NO CONNECTION 7. COMMON ANODE 8. COMMON CATHODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. ANODE/CATHODE 12. ANODE/CATHODE 13. NO CONNECTION 14. COMMON ANODE	STYLE 6: PIN 1. CATHODE 2. CATHODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE 7. CATHODE 8. ANODE 9. ANODE 10. ANODE 11. ANODE 12. ANODE 13. ANODE 14. ANODE	STYLE 7: PIN 1. ANODE/CATHODE 2. COMMON ANODE 3. COMMON CATHODE 4. ANODE/CATHODE 6. ANODE/CATHODE 6. ANODE/CATHODE 7. ANODE/CATHODE 8. ANODE/CATHODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. COMMON CATHODE 12. COMMON ANODE 13. ANODE/CATHODE 14. ANODE/CATHODE	STYLE 8: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. NO CONNECTION 5. ANODE/CATHODE 6. ANODE/CATHODE 7. COMMON ANODE 8. COMMON ANODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. NO CONNECTION 12. ANODE/CATHODE 13. ANODE/CATHODE 14. COMMON CATHODE

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